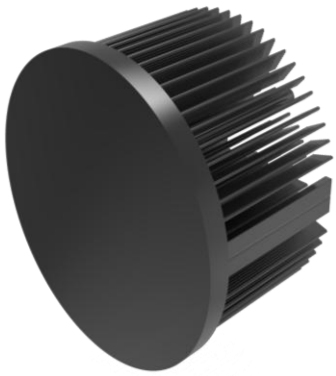
xLED

xLED-13080 Pin Fin LED Heat Sink Φ130mm

Features VS Benefits



* Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages.
* For spotlight and downlight designs from 3,500 to 9,200 lumen.
* Thermal resistance range Rth 0.83°C/W.
* Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COBs.
* Diameter 130.0mm - Standard height 80.0mm , Other heights on request.
* Forged from highly conductive aluminum.

2 standard colors - clear anodized - black anodized.

Zhaga Book 3 Spot Light Modules: Bridgelux ,Cree ,Citizen ,Edison ,GE lighting, LG Innotek ,Lumileds ,Lumens ,Luminus ,Nichia ,Osram ,Philips ,Prolight Opto, Samsung ,Seoul ,Tridonic ,Vossloh-Schwabe ,Xicato.

01) Bridelux: Vero 18/22 Vero SE 18/29 LED engines;
02) Cree: XLamp CXA 25xx, Xlamp CXB 25xx, CXA 30xx, Xlamp CXB 30xx LED en
03) Citizen: CLU036, CLU038, CLU721, CLU711, CLU046, CLU048, CLU731 LED engines;
04) Edison: EdiLex III COB LED engines;
05) GE lighting: Infusion™ LED engines;
06) LG Innotek: 32W, 42W, 56W LED engines;
07) LumiLEDS: LUXEON 1211, LUXEON 1216, LUXEON 1812, LUXEON 1825 LED eng
08) Lumens: Ergon-COB-2530, 2540, 3050, 3070 LED engines;
09) Luminus: CXM-18, CLM-22, CXM-22 LED engines;
10) Nichia: NFCWL036B, NFCLL036B, NFCWL060B, NFCLL060B LED engines;
11) Osram: SOLERIQ® S 19, Core series LED engines;
12) Philips: Fortimo SLM LED engines;
16) Prolight Opto: PABS, PABA, PACB, PANA LED engines;
13) Samsung: LC026B, LC033B, LC040B, LC040D, LC060D, LC080D LED engines;
14) Seoul Semiconductor: Acrich MJT COBs, DC COB LED engines;
15) Tridonic: SLE G6 19mm, SLE G6 23mm LED engines;
17) Vossloh-Schwabe: LUGA Shop and LUGA C LED engines;
18) Xicato: XSM, XIM,XTM LED engines;

Product number

Example:xLED-13080-B

Example:xLED-13080 - 1

1 Anodising Color
B-Black
C-Clear
Z-Custom

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

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Mingfa TECH for LED

xLED

xLED-13080 Pin Fin LED Heat Sink Φ130mm

The Product data table

	Model No.	xLED-13080
	Heatsink Size	Φ130xH80mm
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	825.0
	Dissipated power (Ths-amb,50℃)	60.0 (W)
	Cooling surface area (mm²)	284892
	Thermal Resistance (Rhs-amb)	0.83 (°C/W)

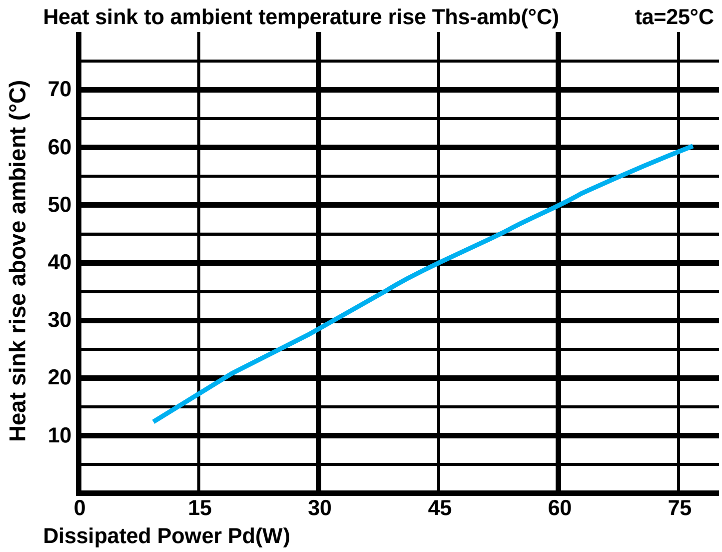
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

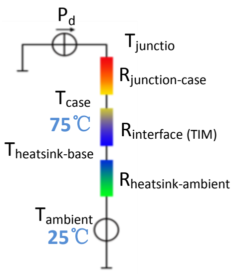
*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		xLED-13080	
Dissipated Power Pd(W)	15.0	1.13	17.0
	30.0	0.93	28.0
	45.0	0.89	40.0
	60.0	0.83	50.0
	75.0	0.77	58.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.
Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a Geometric shapes are different, the thermal resistance is different. Formula: θ =(Ths−Ta)/Pd

θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface\ (TIM)}$ [°C/W], the thermal resistance with heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface\ (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is also used:

$T_{junction}=(R_{junction-case}+R_{case-ambient})\cdot Pd+T_{ambient}$

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